

SEMICONDUCTOR IM

General Description:

Half watt, General purpose, Medium Current Surface Mount Zener in the SOD-123 package. The SOD-123 package has the same footprint as the glass mini-melf (LL-34) package & provides a convenient alternative to the Leadless package.

DISCRETE POWER AND SIGNAL TECHNOLOGIES

Features:

MMSZ5226B

5% TOLERANCE

- Compact surface mount with same footprint as mini-melf
- 500 mW rating on FR-4 or FR-5 board.
- Class 3 ESD rating (>16 kV) per Human Body Model

Ordering:

• 7 inch reel (178 mm); 8 mm Tape; 3,000 units per reel.

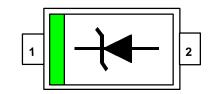
Absolute Maximum Ratings (note 1) TA = 25°C unless otherwise noted

| Parameter | Value | Units |
|---|-------------|--------------------|
| Storage Temperature | -55 to +150 | °C |
| Maximum Junction Temperature | -55 to +150 | OO |
| Total Power Dissipation at 25 ^o C | 500 | mW |
| Derate above 25 ⁰ C | 6.7 | mW/ ^o C |
| Thermal Resistance ($R_{ØJA}$) Junction to Ambient (note 2) | 340 | °C/W |
| Maximum Temperature Coefficient | -0.070 | %/ ⁰ C |
| Nominal Zener Voltage (V _z) at 20 mA | 3.3 | V |

Note 1: These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

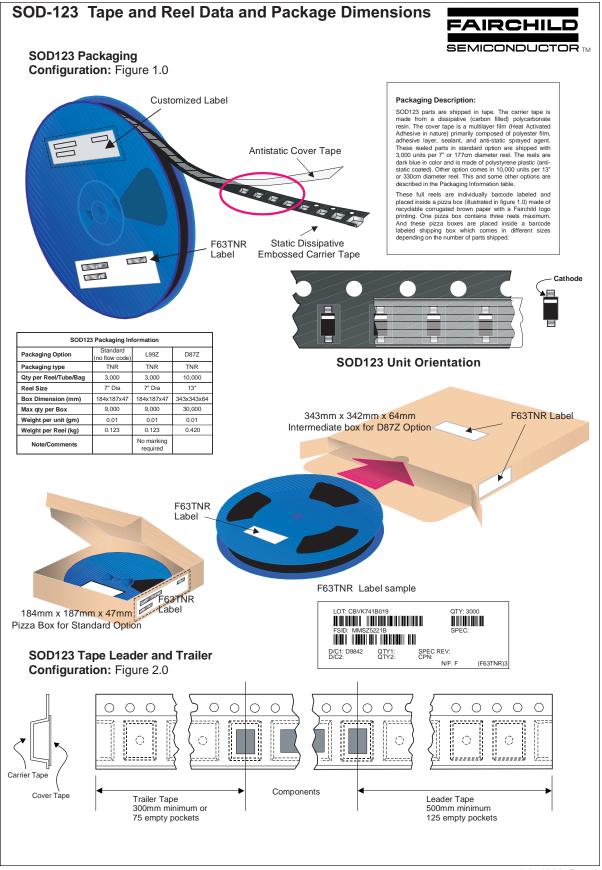
Note 2: FR-4 or FR-5 = 3.5×1.5 inches using minimum recommended Land Pads.

Top Mark: **D1** 1: Cathode 2: Anode

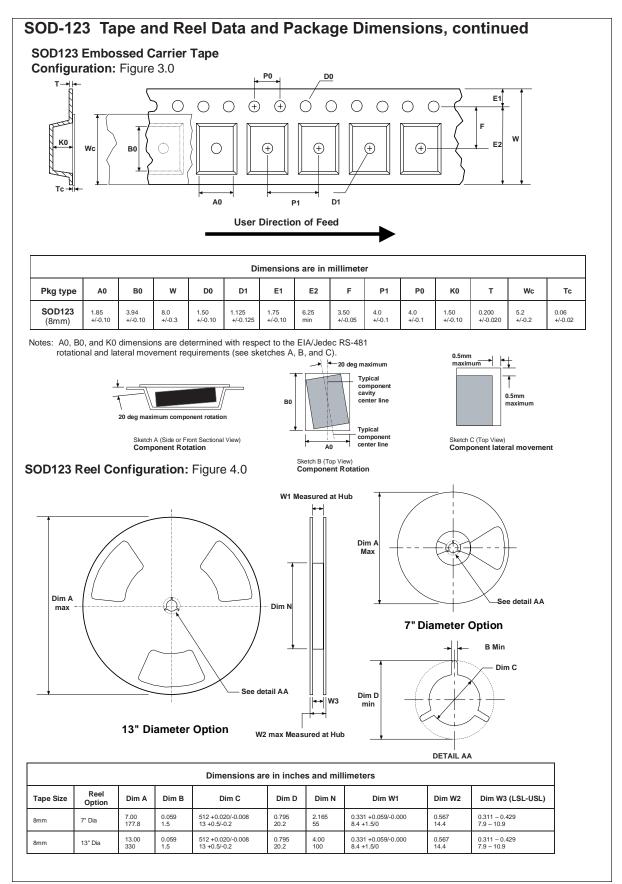


Electrical Characteristics TA = 25°C unless otherwise noted

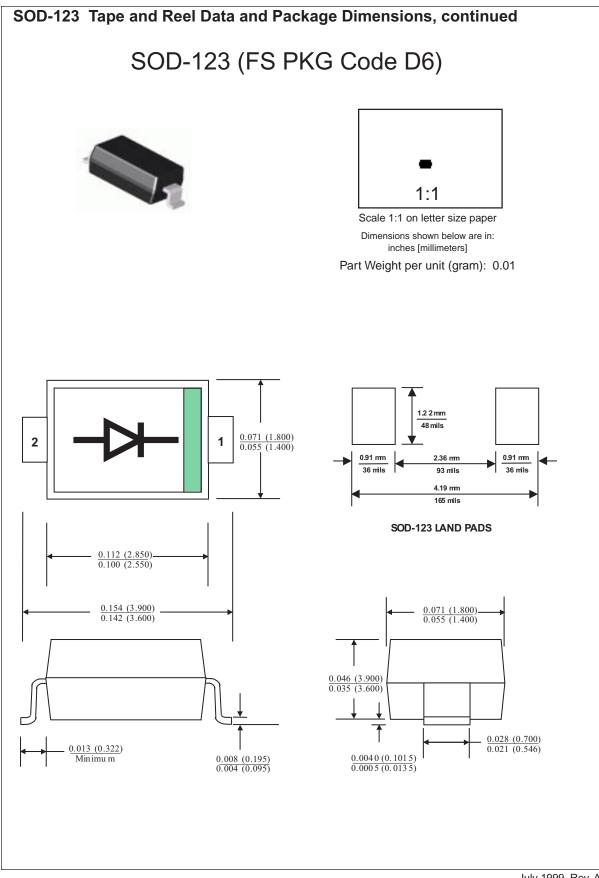
| SYM | CHARACTERISTICS | MIN | МАХ | UNITS | TEST CONDITIONS |
|------------------|--|----------------|----------------|--------|---|
| Vz | Zener Voltage | 3.135 3.160 | 3.465 3.490 | V V | $I_{ZT} = 20.0 \text{ mA D.C.}$ $I_{ZT} = 20.0 \text{ mA Pulse 26 mS}$ |
| Zz | Zener Impedance | | 28.0 | Ohms | $I_{ZT} = 20.0 \text{ mA}$ |
| Z _{ZK} | Zener Knee Impedance | | 1,600 | Ohms | I _{ZK} = 250 uA |
| I _R | Reverse Leakage | | 25 | uA | $V_{R} = 1.0 V$ |
| V _F | Forward Voltage | | 900 | mV | I _F = 10 mA |
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PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|---------------------------|---|
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